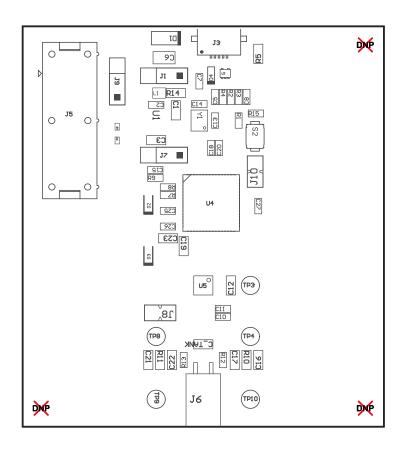
ZZ1 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZZ ■ This Assembly Note will show in the PcbDoc and associated outputs

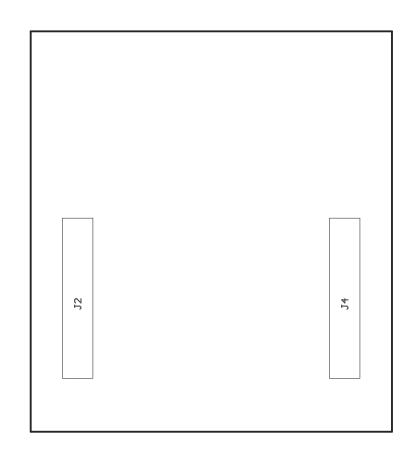
ZZ3 ■ This Assembly Note will show in the PcbDoc and associated outputs

ZZ4 ■ This Assembly Note will show in the PcbDoc and associated outputs



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00563	REV: E1	SUN REU: N	Not In VersionControl
LAYER NAME = M5 Assembly Top				
PLOT NAME=Top Assembly Drawing	GENERATED	: 10/19/2015	1:39:01 PM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00563	REV: E1	SUN REU	: Not In VersionControl	
	LAYER NAME = M6 Assembly Bottom				
PLOT NAME =Bottom Assembly Drawing	GENERATED	: 10/19/2015	1:39:02 PM	TEXAS INSTRUMENTS	

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